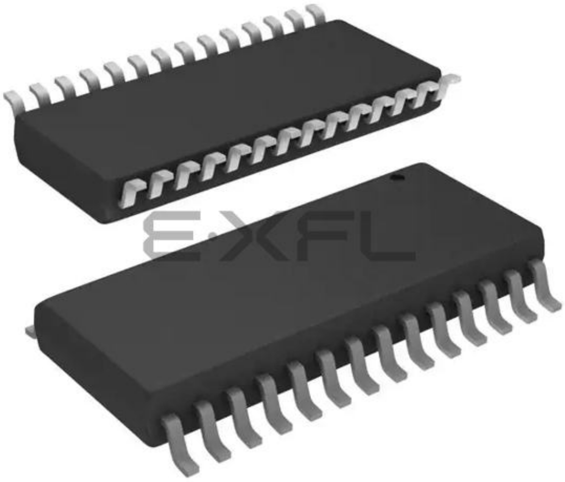
Microchip Technology - DSPIC33FJ16GP102T-I/SO Datasheet



Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gp102t-i-so

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70204) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 CPU module has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for DSP. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can serve as a data, address, or address offset register. The 16th Working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

There are two classes of instruction in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices: MCU and DSP. These two instruction classes are seamlessly integrated into a single CPU. The instruction set includes many addressing modes and is designed for optimum C compiler efficiency. For most instructions, dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices are capable of executing a data (or program data) memory read, a Working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1, and the programmer's model for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be addressed as 32K words or 64 Kbytes and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear data space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y data space boundary is device-specific.

Overhead-free circular buffers (Modulo Addressing mode) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. Furthermore, the X AGU circular addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page (PSVPAG) register. The program-to-data-space mapping feature lets any instruction access program space as if it were data space.

3.2 DSP Engine Overview

The DSP engine features a high-speed, 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left, in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The `MAC` instruction and other associated instructions can concurrently fetch two data operands from memory, while multiplying two W registers and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner through dedicating certain Working registers to each address space.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **“Data Memory”** (DS70202) and **“Program Memory”** (DS70203) in the *“dsPIC33/PIC24 Family Reference Manual”*, which are available from the Microchip web site (www.microchip.com).

The device architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the data space during code execution.

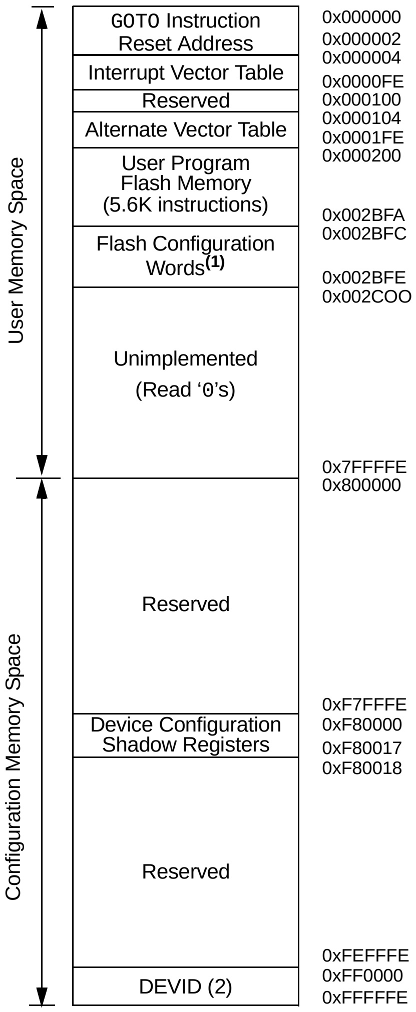
4.1 Program Address Space

The program address memory space of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit Program Counter (PC) during program execution, or from table operation or data space remapping as described in **Section 4.6 “Interfacing Program and Data Memory Spaces”**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of `TBLRD/TBLWT` operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

The memory maps for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family of devices are shown in Figure 4-1 and Figure 4-2.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33FJ16(GP/MC)101/102 DEVICES



Note 1: On Reset, these bits are automatically copied into the device Configuration Shadow registers.

TABLE 4-26: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33FJ32(GP/MC)104 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	06C0	—	—	—	RP1R<4:0>					—	—	—	RP0R<4:0>					0000
RPOR1	06C2	—	—	—	RP3R<4:0>					—	—	—	RP2R<4:0>					0000
RPOR2	06C4	—	—	—	RP5R<4:0>					—	—	—	RP4R<4:0>					0000
RPOR3	06C6	—	—	—	RP7R<4:0>					—	—	—	RP6R<4:0>					0000
RPOR4	06C8	—	—	—	RP9R<4:0>					—	—	—	RP8R<4:0>					0000
RPOR5	06CA	—	—	—	RP11R<4:0>					—	—	—	RP10R<4:0>					0000
RPOR6	06CC	—	—	—	RP13R<4:0>					—	—	—	RP12R<4:0>					0000
RPOR7	06CE	—	—	—	RP15R<4:0>					—	—	—	RP14R<4:0>					0000
RPOR8	06D0	—	—	—	RP17R<4:0>					—	—	—	RP16R<4:0>					0000
RPOR9	06D2	—	—	—	RP19R<4:0>					—	—	—	RP18R<4:0>					0000
RPOR10	06D4	—	—	—	RP21R<4:0>					—	—	—	RP20R<4:0>					0000
RPOR11	06D6	—	—	—	RP23R<4:0>					—	—	—	RP22R<4:0>					0000
RPOR12	06D8	—	—	—	RP25R<4:0>					—	—	—	RP24R<4:0>					0000

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-27: PORTA REGISTER MAP FOR dsPIC33FJ16(GP/MC)101/102 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	—	—	—	—	—	—	—	—	—	—	—	TRISA<4:0>					001F
PORTA	02C2	—	—	—	—	—	—	—	—	—	—	—	RA<4:0					xxxx
LATA	02C4	—	—	—	—	—	—	—	—	—	—	—	LATA<4:0					xxxx
ODCA	02C6	—	—	—	—	—	—	—	—	—	—	—	ODCA<4:2>			—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-28: PORTA REGISTER MAP FOR dsPIC33FJ32(GP/MC)101/102 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	—	—	—	—	—	—	—	—	—	—	—	TRISA<4:0>					001F
PORTA	02C2	—	—	—	—	—	—	—	—	—	—	—	RA<4:0					xxxx
LATA	02C4	—	—	—	—	—	—	—	—	—	—	—	LATA<4:0					xxxx
ODCA	02C6	—	—	—	—	—	—	—	—	—	—	—	—	ODCA<3:2>		—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

4.4.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

It is important to realize that the address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset (such as [W7 + W2]) is used, Modulo Addressing correction is performed, but the contents of the register remain unchanged.

4.5 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.5.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled in any of these situations:

- BWM<3:0> bits (W register selection) in the MODCON register are any value other than ‘15’ (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last ‘N’ bits of the data buffer start address must be zeros.

XB<14:0> is the bit-reversed address modifier, or ‘pivot point,’ which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note:	All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB<14:0> value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It will not function for any other addressing mode or for byte-sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	Modulo Addressing and Bit-Reversed Addressing should not be enabled together. If an application attempts to do so, Bit-Reversed Addressing will assume priority when active. For the X WAGU and Y AGU, Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**ALTIVT:** Enable Alternate Interrupt Vector Table bit `1` = Uses Alternate Interrupt Vector Table `0` = Uses standard Interrupt Vector Table (default)
bit 14	**DISI:** `DISI` Instruction Status bit `1` = `DISI` instruction is active `0` = `DISI` instruction is not active
bit 13-3	**Unimplemented:** Read as ‘`0`’
bit 2	**INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit `1` = Interrupt on negative edge `0` = Interrupt on positive edge
bit 1	**INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit `1` = Interrupt on negative edge `0` = Interrupt on positive edge
bit 0	**INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit `1` = Interrupt on negative edge `0` = Interrupt on positive edge

REGISTER 7-5: IFS0: INTERRUPT FLAG STATUS REGISTER 0 (CONTINUED)

bit 2	**OC1IF:** Output Compare Channel 1 Interrupt Flag Status bit `1` = Interrupt request has occurred `0` = Interrupt request has not occurred
bit 1	**IC1IF:** Input Capture Channel 1 Interrupt Flag Status bit `1` = Interrupt request has occurred `0` = Interrupt request has not occurred
bit 0	**INT0IF:** External Interrupt 0 Flag Status bit `1` = Interrupt request has occurred `0` = Interrupt request has not occurred

REGISTER 9-3: PMD3: PERIPHERAL MODULE DISABLE CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	CMPMD	RTCCMD	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11	**Unimplemented:** Read as ‘0’
bit 10	**CMPMD:** Comparator Module Disable bit 1 = Comparator module is disabled 0 = Comparator module is enabled
bit 9	**RTCCMD:** RTCC Module Disable bit 1 = RTCC module is disabled 0 = RTCC module is enabled
bit 8-0	**Unimplemented:** Read as ‘0’

REGISTER 9-4: PMD4: PERIPHERAL MODULE DISABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	—	—	—	—	CTMUMD	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3	**Unimplemented:** Read as ‘0’
bit 2	**CTMUMD:** CTMU Module Disable bit 1 = CTMU module is disabled 0 = CTMU module is enabled
bit 1-0	**Unimplemented:** Read as ‘0’

10.7 Peripheral Pin Select Registers

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family of devices implements up to 23 registers for remappable peripheral configuration.

Note:	Input and output register values can only be changed if IOLOCK (OSCCON<6>) = `0`. See **Section 10.4.3.1 "Control Register Lock"** for a specific command sequence.

REGISTER 10-1: RPINR0: PERIPHERAL PIN SELECT INPUT REGISTER 0

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	INT1R4	INT1R3	INT1R2	INT1R1	INT1R0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '`0`'

bit 12-8 **INT1R<4:0>:** Assign External Interrupt 1 (INTR1) to the Corresponding RPn Pin bits

`11111` = Input tied to Vss
`11110` = Reserved
.
.
.
`11010` = Reserved
`11001` = Input tied to RP25
.
.
.
`00001` = Input tied to RP1
`00000` = Input tied to RP0

bit 7-0 **Unimplemented:** Read as '`0`'

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 device families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Real-Time Clock and Calendar (RTCC)"** (DS70310) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This chapter discusses the Real-Time Clock and Calendar (RTCC) module, available on dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices, and its operation.

Some of the key features of the RTCC module are:

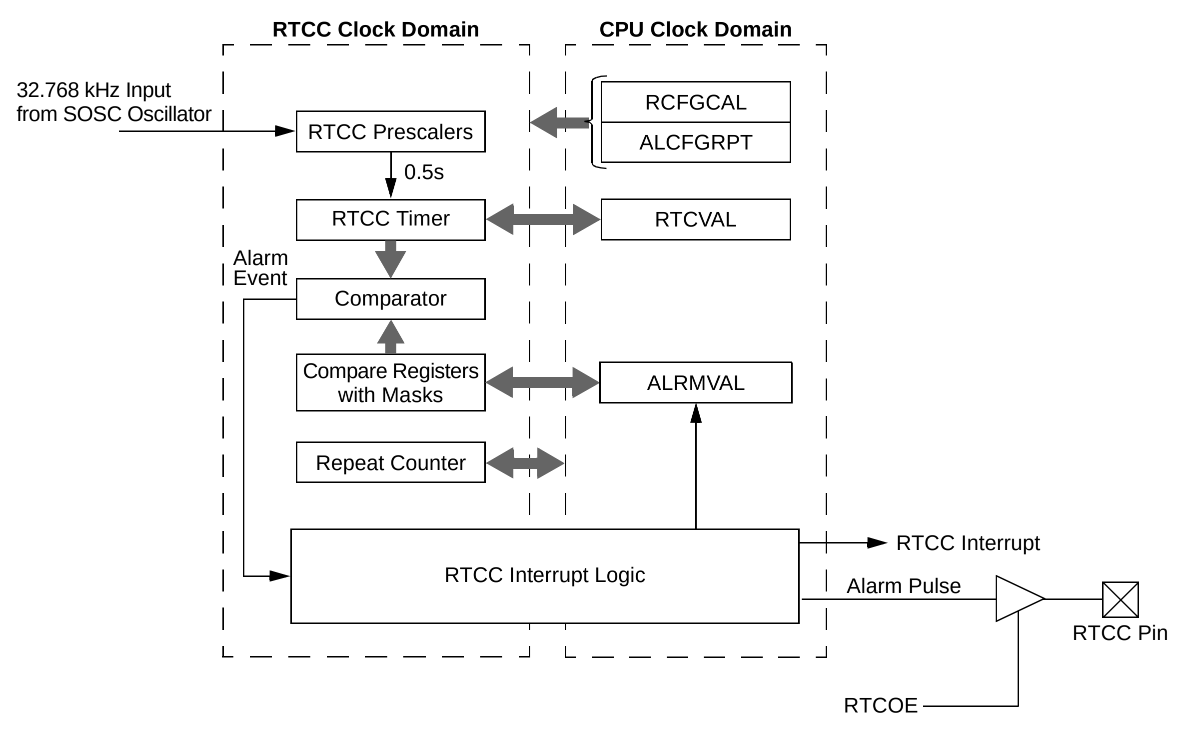
- Time: hours, minutes and seconds
- 24-hour format (military time)
- Calendar: weekday, date, month and year
- Alarm configurable
- Year range: 2000 to 2099
- Leap year correction
- BCD format for compact firmware
- Optimized for low-power operation
- User calibration with auto-adjust
- Calibration range: ±2.64 seconds error per month
- Requirements: external 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

The RTCC module is intended for applications where accurate time must be maintained for extended periods of time with minimum to no intervention from the CPU. The RTCC module is optimized for low-power usage to provide extended battery lifetime while keeping track of time.

The RTCC module is a 100-year clock and calendar with automatic leap year detection. The range of the clock is from 00:00:00 (midnight) on January 1, 2000 to 23:59:59 on December 31, 2099.

The hours are available in 24-hour (military time) format. The clock provides a granularity of one second with half-second visibility to the user.

FIGURE 21-1: RTCC BLOCK DIAGRAM



REGISTER 21-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1) (CONTINUED)

bit 7-0 **CAL<7:0>:** RTC Drift Calibration bits

`01111111` = Maximum positive adjustment; adds 508 RTC clock pulses every one minute
•
•
•
`00000001` = Minimum positive adjustment; adds 4 RTC clock pulses every one minute
`00000000` = No adjustment
`11111111` = Minimum negative adjustment; subtracts 4 RTC clock pulses every one minute
•
•
•
`10000000` = Maximum negative adjustment; subtracts 512 RTC clock pulses every one minute

Note 1: The RCFGCAL register is only affected by a POR.
2: A write to the RTCEN bit is only allowed when RTCWREN = `1`.
3: This bit is read-only; it is cleared to ‘`0`’ on a write to the lower half of the MINSEC register.

REGISTER 21-6: RTCVAL (WHEN RTCPTR<1:0> = `01`): RTCC WEEKDAY AND HOURS VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11	**Unimplemented:** Read as ‘`0`’
bit 10-8	**WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits Contains a value from 0 to 6.
bit 7-6	**Unimplemented:** Read as ‘`0`’
bit 5-4	**HRTEN<1:0>:** Binary Coded Decimal Value of Hour’s Tens Digit bits Contains a value from 0 to 2.
bit 3-0	**HRONE<3:0>:** Binary Coded Decimal Value of Hour’s Ones Digit bits Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = `1`.

22.1 CTMU Control Registers

REGISTER 22-1: CTMUCON1: CTMU CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN[1]	EDGEN	EDGSEQEN	IDISSEN[2]	CTTRIG
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit

1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit[1]

1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit

1 = Edges are not blocked
0 = Edges are blocked

bit 10 **EDGSEQEN:** Edge Sequence Enable bit

1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit[2]

1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** CTMU Trigger Control bit

1 = Trigger output is enabled
0 = Trigger output is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: If TGEN = 1, the peripheral inputs and outputs must be configured to an available RPn pin. For more information, see **Section 10.4 “Peripheral Pin Select (PPS)”**.

2: The ADC module S&H capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘1’, performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

23.2 On-Chip Voltage Regulator

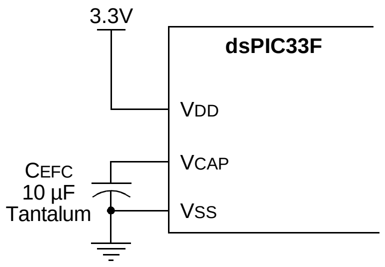
All of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 23-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 26-14 located in **Section 26.1 "DC Characteristics"**.

Note: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 µs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 23-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 26-14 located in **Section 26.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

23.3 BOR: Brown-out Reset

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an Oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = `0` and a crystal oscillator is being used, then a nominal delay of TFSCM = `100` is applied. The total delay in this case is TFSCM.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
48	MPY	MPY Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		MPY Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
49	MPY.N	MPY.N Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	(Multiply Wm by Wn) to Accumulator	1	1	None
50	MSC	MSC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd, AWB	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
51	MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None
52	NEG	NEG Acc	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG f	f = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG f,WREG	WREG = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
53	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
54	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
55	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
56	PWRSAV	PWRSAV #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
57	RCALL	RCALL Expr	Relative Call	1	2	None
		RCALL Wn	Computed Call	1	2	None
58	REPEAT	REPEAT #lit14	Repeat Next Instruction lit14 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
59	RESET	RESET	Software device Reset	1	1	None
60	RETFIE	RETFIE	Return from interrupt	1	3 (2)	None
61	RETLW	RETLW #lit10,Wn	Return with literal in Wn	1	3 (2)	None
62	RETURN	RETURN	Return from Subroutine	1	3 (2)	None
63	RLC	RLC f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
64	RLNC	RLNC f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
65	RRC	RRC f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z

TABLE 26-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock On Base Current(2) – dsPIC33FJ32(GP/MC)10X Devices						
DC40d	0.4	1.0	mA	-40°C	3.3V	LPRC (32.768 kHz)(3)
DC40a	0.4	1.0	mA	+25°C		
DC40b	0.4	1.0	mA	+85°C		
DC40c	0.5	1.0	mA	+125°C		
DC41d	0.5	1.1	mA	-40°C	3.3V	1 MIPS(3)
DC41a	0.5	1.1	mA	+25°C		
DC41b	0.5	1.1	mA	+85°C		
DC41c	0.8	1.1	mA	+125°C		
DC42d	0.9	1.6	mA	-40°C	3.3V	4 MIPS(3)
DC42a	0.9	1.6	mA	+25°C		
DC42b	1.0	1.6	mA	+85°C		
DC42c	1.2	1.6	mA	+125°C		
DC43a	1.6	2.6	mA	+25°C	3.3V	10 MIPS(3)
DC43d	1.6	2.6	mA	-40°C		
DC43b	1.7	2.6	mA	+85°C		
DC43c	2.0	2.6	mA	+125°C		
DC44d	2.4	3.8	mA	-40°C	3.3V	16 MIPS(3)
DC44a	2.4	3.8	mA	+25°C		
DC44b	2.6	3.8	mA	+85°C		
DC44c	2.9	3.8	mA	+125°C		

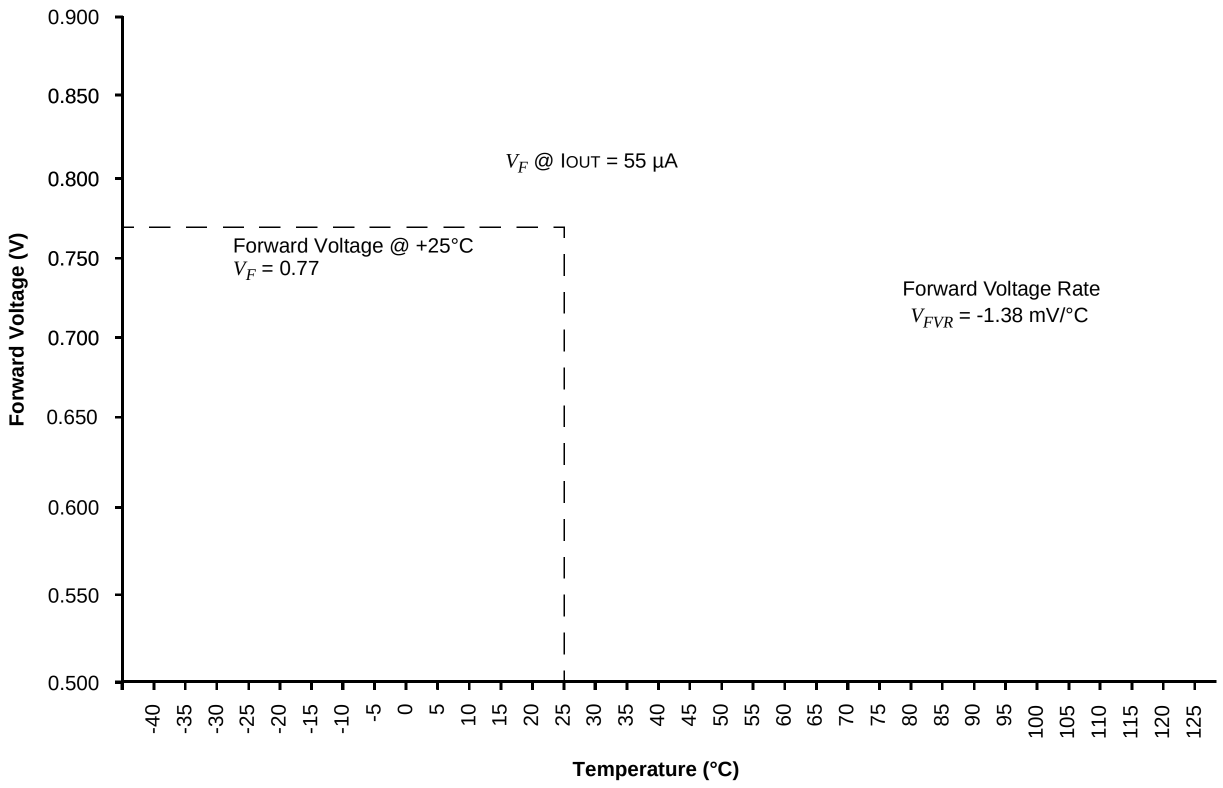
Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

2: Base Idle current is measured as follows:

- CPU core is off, oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- External Secondary Oscillator (SOSC) is disabled (i.e., SOSCO and SOSCI pins are configured as digital I/O inputs)
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)

3: These parameters are characterized, but not tested in manufacturing.

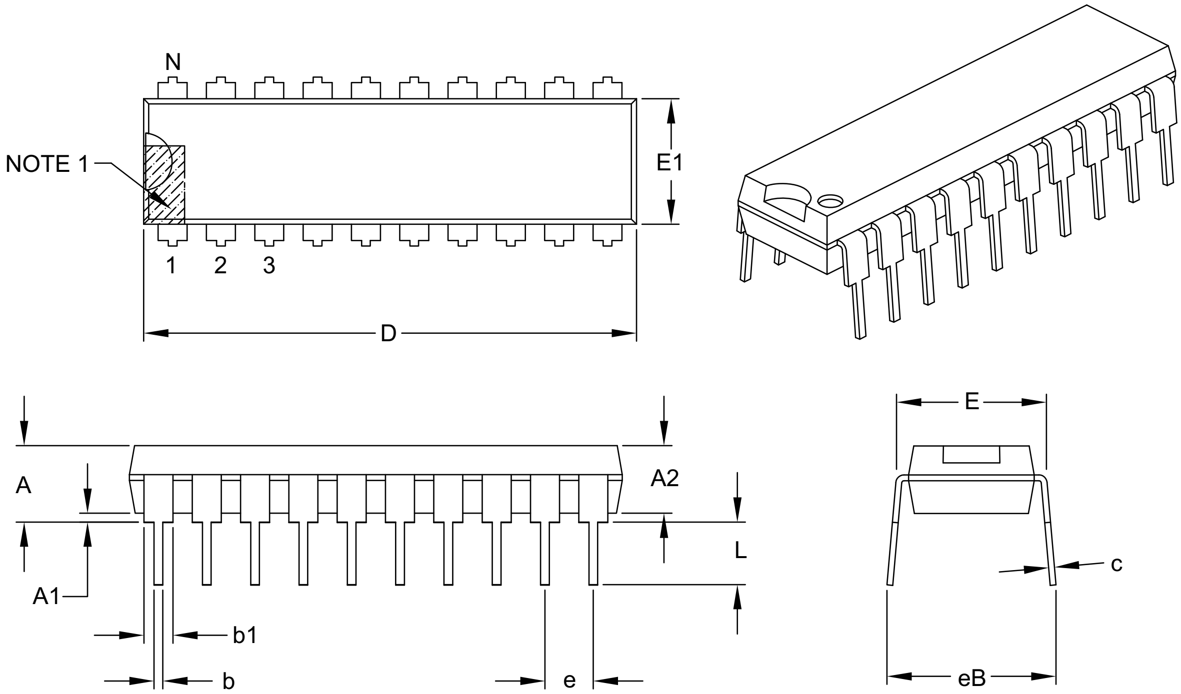
FIGURE 26-33: FORWARD VOLTAGE VERSUS TEMPERATURE



Note: This graph is a statistical summary based on a limited number of samples and this data is characterized but not tested in manufacturing.

20-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES		
Units				
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.980	1.030	1.060
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

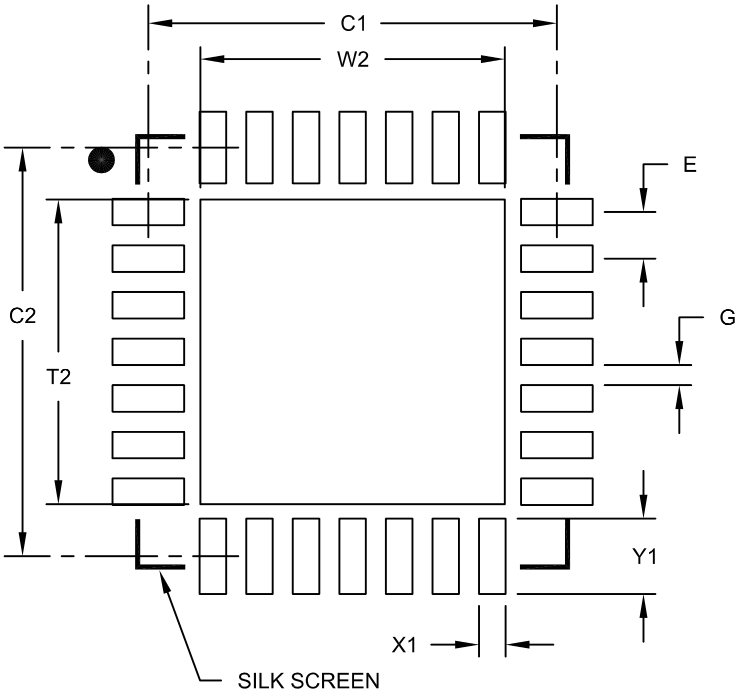
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-019B

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

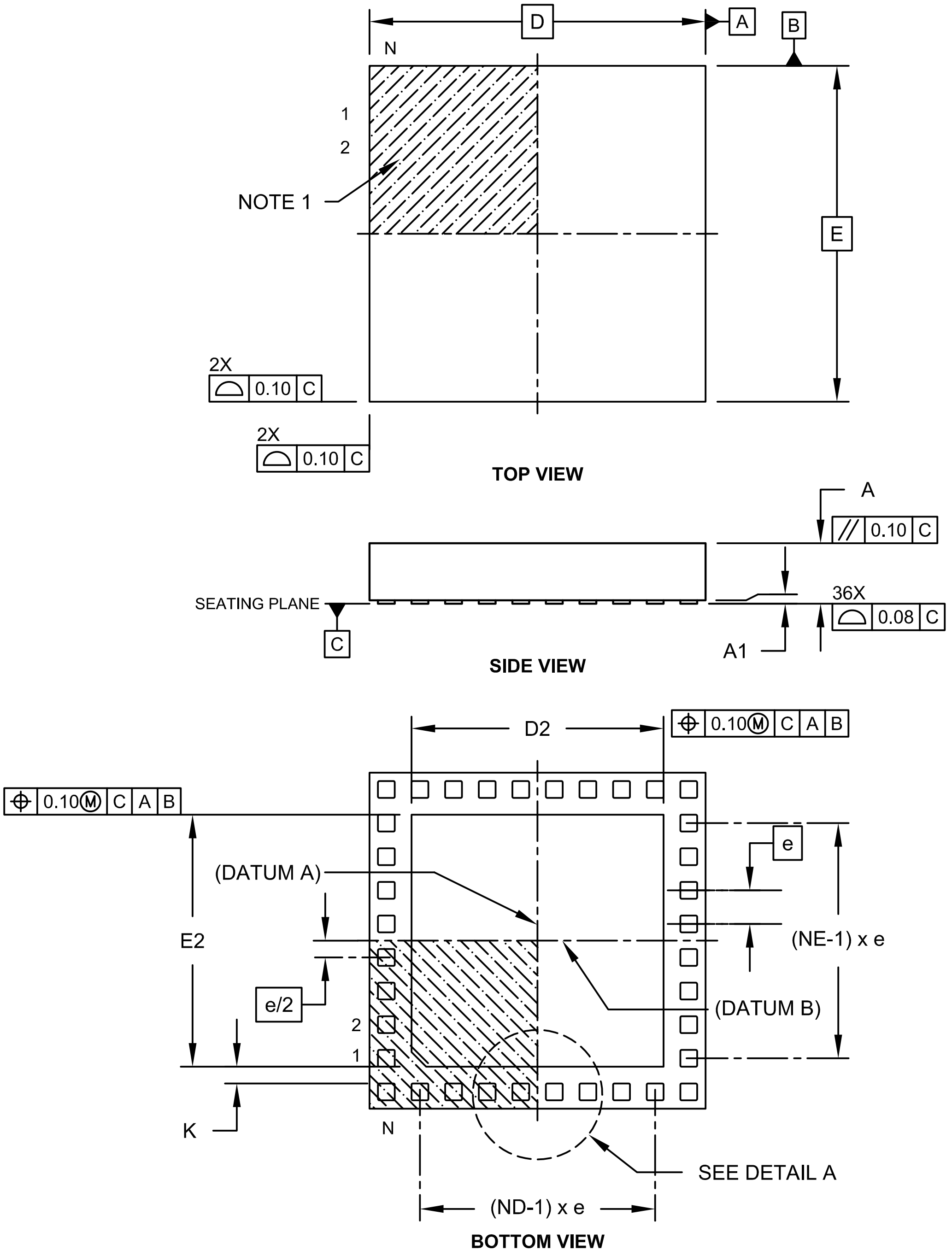
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

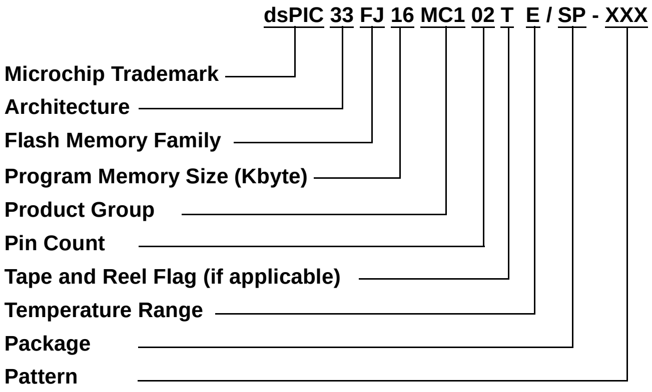
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-187C Sheet 1 of 2

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Architecture:	33	=	16-bit Digital Signal Controller
Flash Memory Family:	FJ	=	Flash program memory, 3.3V
Product Group:	GP1	=	General Purpose family
	MC1	=	Motor Control family
Pin Count:	01	=	18-pin and 20-pin
	02	=	28-pin and 32-pin
Temperature Range:	I	=	-40°C to +85°C (Industrial)
	E	=	-40°C to +125°C (Extended)
Package:	P	=	Plastic Dual In-Line - 300 mil body (PDIP)
	SS	=	Plastic Shrink Small Outline - 5.3 mm body (SSOP)
	SP	=	Skinny Plastic Dual In-Line - 300 mil body (SPDIP)
	SO	=	Plastic Small Outline - Wide - 7.50 mil body (SOIC)
	ML	=	Plastic Quad, No Lead - (28-pin) 6x6 mm body (QFN)
	PT	=	Plastic Thin Quad Flatpack - (44-pin) 10x10 mm body (TQFP)
	TL	=	Very Thin Leadless Array - (36-pin) 5x5 mm body (VTLA)

Examples:

a) dsPIC33FJ16MC102-E/SP:
Motor Control dsPIC33,
16-Kbyte Program Memory,
28-Pin, Extended Temperature,
SPDIP package.